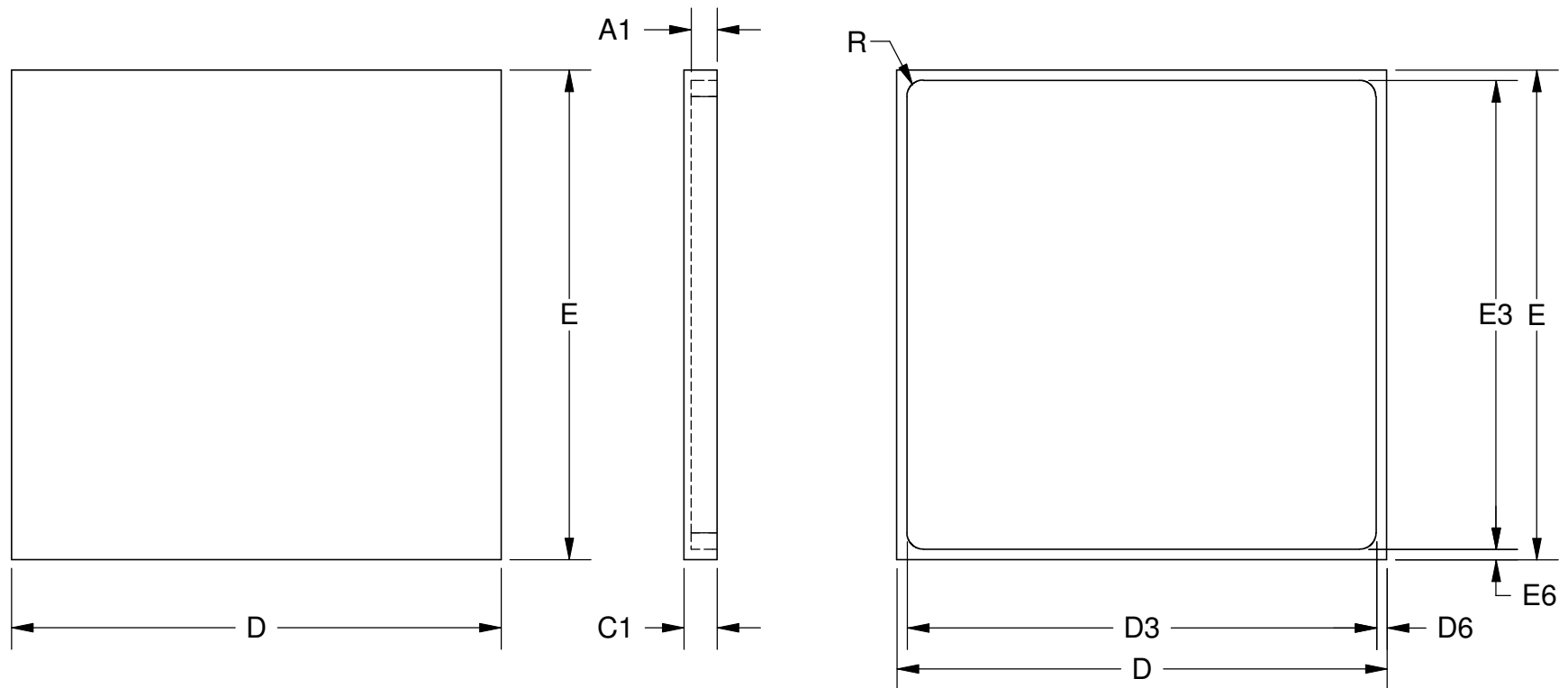


TOP VIEW
CLOSED SIDE

SIDE VIEW

BOTTOM VIEW
OPEN SIDE



WITHOUT EPOXY PREFORM

WITHOUT EPOXY PREFORM							SUBSTRATE MATERIAL	
mm	INCH	mm	INCH	mm	mm	mm	DWG NBR BT	DWG NBR RO4003C
D/E	D/E	D3/E3	D3/E3	D6/E6	A1	C1	BLACK	WHITE
3	0.118	2.5	0.098	0.25	0.55	0.81	203100	203940
4	0.157	3.5	0.137	0.25	0.55	0.81	204100	204940
5	0.197	4.5	0.177	0.25	0.55	0.81	205100	205940
6	0.236	5.5	0.216	0.25	0.55	0.81	206100	206940
7	0.276	6.5	0.256	0.25	0.55	0.81	207100	207940
8	0.315	7.5	0.295	0.25	0.55	0.81	208100	208940
9	0.354	8.5	0.334	0.25	0.55	0.81	209100	209940
10	0.394	9.5	0.374	0.25	0.55	0.81	210100	210940
12	0.472	11.5	0.453	0.25	0.55	0.81	212100	212940

Notes: (Unless Otherwise Specified).

- 1) MATERIAL: SEE PART NUMBER CHART.
- 2) PIN 1 MARKING: None.
- 3) CAVITY IS MILLED.
- 4) ROUTING DIMENSION "R" 0.031 INCH (0.80 mm) MAX.

Mirror Semiconductor™			
TITLE		R-CAP DOME LID MILLED ASSEMBLY	
SCALE	SIZE	DRAWING NO.	REV
6:1	A	200003	A
DO NOT SCALE DRAWING			SHEET 2 OF 3